

## UltraVt<sup>®</sup> Depletion-Mode Power MOSFET

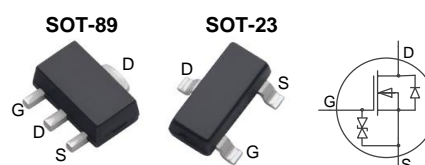
### General Features

- ESD Improved Capability
- Depletion Mode (Normally On)
- Proprietary Advanced Planar Technology
- Proprietary Advanced Ultrahigh V<sub>th</sub> Technology
- RoHS Compliant
- Halogen-free Available

BV <sub>DSX</sub>	V <sub>GS(off)</sub>	I <sub>DSS,min</sub>
<b>130V</b>	<b>-17V to -27V</b>	<b>100mA</b>

### Applications

- Quick Charger
- Current Source
- Voltage Source
- Type-C/PD charger



### General Description

This novel depletion mode MOSFET, developed and manufactured by ARK proprietary UltraVt<sup>®</sup> technology. It has a high threshold voltage. By using the sub threshold characteristics, the depletion mode MOSFET can provide stably power to the load, and the voltage can be clamped to protect the load without Zener diode, and the circuit consumption is reduced.

### Ordering Information

Part Number	Package	Marking	Remark
DMZ1315E	SOT-23	1315	Halogen Free
DMX1315E	SOT-89	1315	Halogen Free

### Absolute Maximum Ratings

T<sub>A</sub>=25°C unless otherwise specified

Symbol	Parameter	DMZ1315E	DMX1315E	Unit
V <sub>DSX</sub>	Drain-to-Source Voltage <sup>[1]</sup>	130		V
I <sub>D</sub>	Continuous Drain Current	0.1		A
I <sub>DM</sub>	Pulsed Drain Current <sup>[2]</sup>	0.4		
P <sub>D</sub>	Power Dissipation	0.5	1.0	W
V <sub>GS</sub>	Gate-to-Source Voltage	±30		V
V <sub>ESD</sub>	Gate to Source ESD <sup>[3]</sup>	700		V
	Source to Gate ESD <sup>[3]</sup>	700		V
T <sub>L</sub>	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300		°C
T <sub>J</sub> and T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to 150		

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

### Thermal Characteristics

Symbol	Parameter	DMZ1315E	DMX1315E	Unit
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	250	125	K/W

## Electrical Characteristics

### OFF Characteristics

 $T_A = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$BV_{DSX}$	Drain-to-Source Breakdown Voltage	130	--	--	V	$V_{GS} = -30\text{V}$ , $I_D = 250\mu\text{A}$
$I_{D(OFF)}$	Drain-to-Source Leakage Current	--	--	10	$\mu\text{A}$	$V_{DS} = 130\text{V}$ , $V_{GS} = -30\text{V}$
$I_{GSS}$	Gate-to-Source Leakage Current	--	--	20	$\mu\text{A}$	$V_{GS} = +30\text{V}$ , $V_{DS} = 0\text{V}$
		--	--	-20		$V_{GS} = -30\text{V}$ , $V_{DS} = 0\text{V}$

### ON Characteristics

 $T_A = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$I_{DSS}$	Saturated Drain-to-Source Current	100	--	--	mA	$V_{GS} = 0\text{V}$ , $V_{DS} = 25\text{V}$
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	--	11	30	$\Omega$	$V_{GS} = 0\text{V}$ , $I_D = 50\text{mA}$ <sup>[4]</sup>
$V_{GS(OFF)}$	Gate-to-Source Cut-off Voltage	-17	--	-27	V	$V_{DS} = 9\text{V}$ , $I_D = 8\mu\text{A}$
$V_{CL}$	Source-to-Gate Clamp Voltage	-11.5	--	--	V	$V_{DS} = 9\text{V}$ , $I_D = 5\text{mA}$

### Source-Drain Diode Characteristics

 $T_A = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Min	Typ.	Max.	Units	Test Conditions
$V_{SD}$	Diode Forward Voltage	--	--	1.2	V	$I_{SD} = 100\text{mA}$ , $V_{GS} = -30\text{V}$

**NOTE:**

[1]  $T_J = +25^\circ\text{C}$  to  $+150^\circ\text{C}$

[2] Repetitive rating, pulse width limited by maximum junction temperature.

[3] The test is based on JEDEC EIA/JESD22-A114 (HBM).

[4] Pulse width  $\leq 380\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

## Typical and highlight Characteristics

DMZ1315E/DMX1315E is an UltraVt<sup>®</sup> depletion mode MOS device. A stable output voltage source or current source is implemented by using the sub-threshold characteristics of the device. Its basic application is shown as Figure 1:

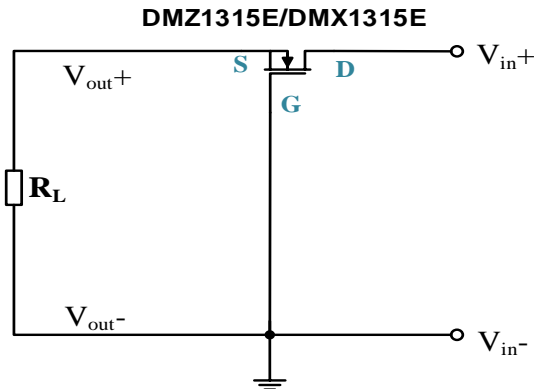


Figure1. Drain Current  $I_D$  is decided by Load Resistance

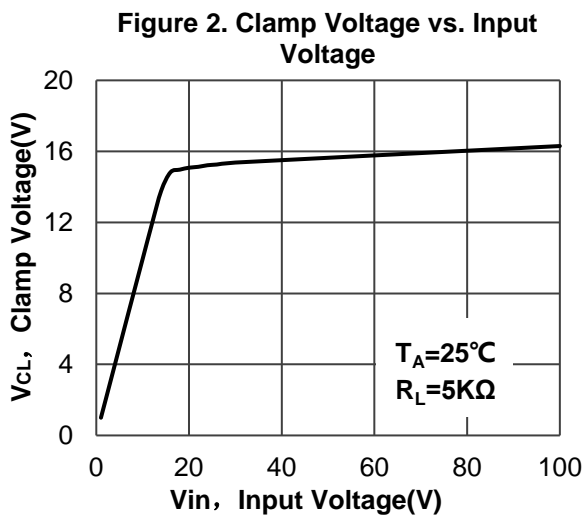


Figure 2. Clamp Voltage vs. Input Voltage

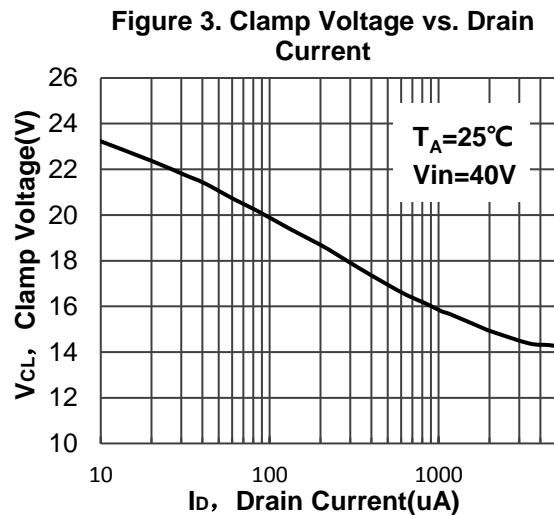


Figure 3. Clamp Voltage vs. Drain Current

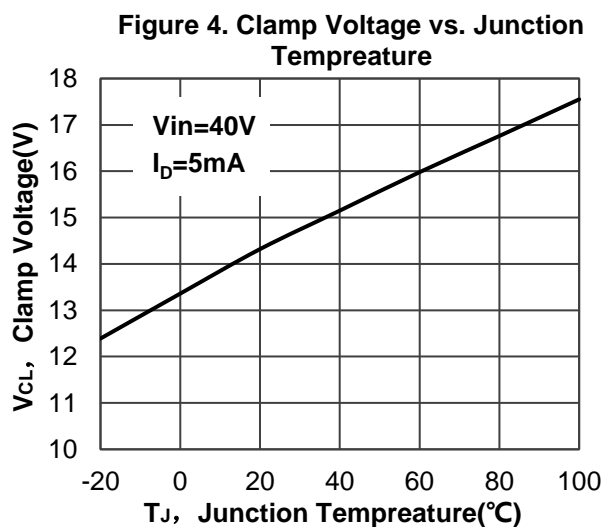
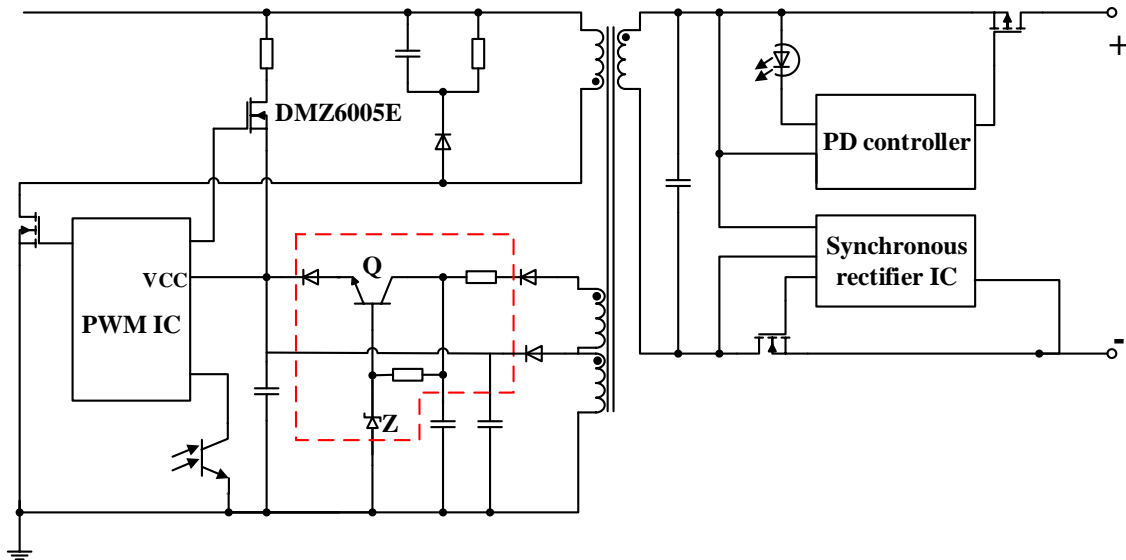


Figure 4. Clamp Voltage vs. Junction Temperature

## Typical Application

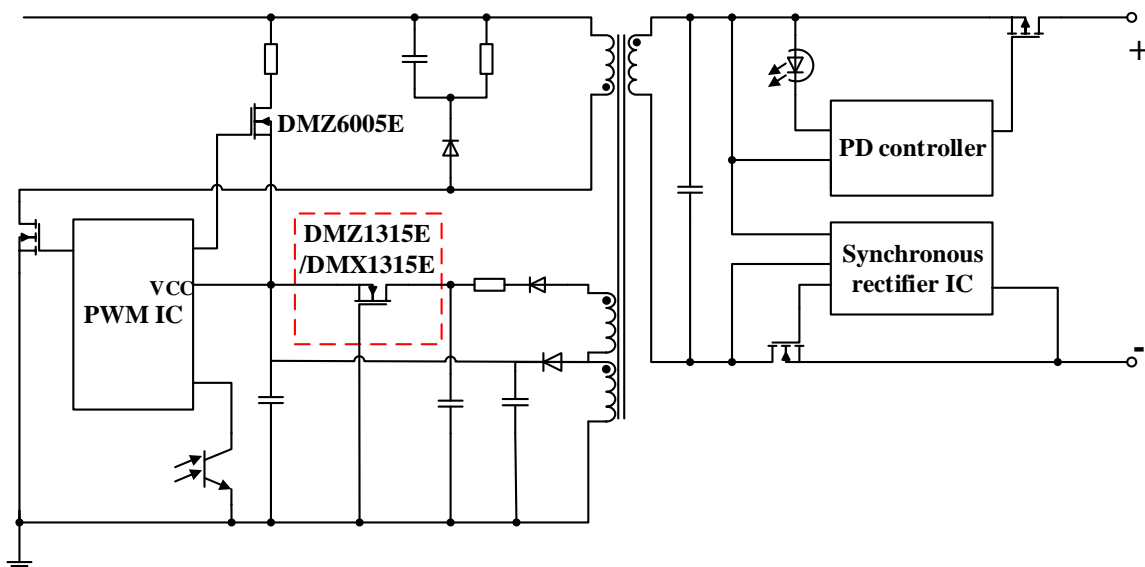
In the QC2.0/3.0 and Type-C/PD charger circuits, using DMZ1315E/DMX1315E as a high voltage linear regulators can make the PWM IC power supply circuit more simplified, as shown below:

In Figure 5, the transistor Q is used to provide power, and the zener diode Z is used to clamp voltage, the power supply circuit of IC is composed of several components.



**Figure 5. Normal Circuit with Transistor and Diode**

In Figure 6, providing power and clamp voltage use only one device—DMZ1315E/DMX1315E, the circuit is simplified.



**Figure 6. Circuit with DMZ1315E/DMX1315E**

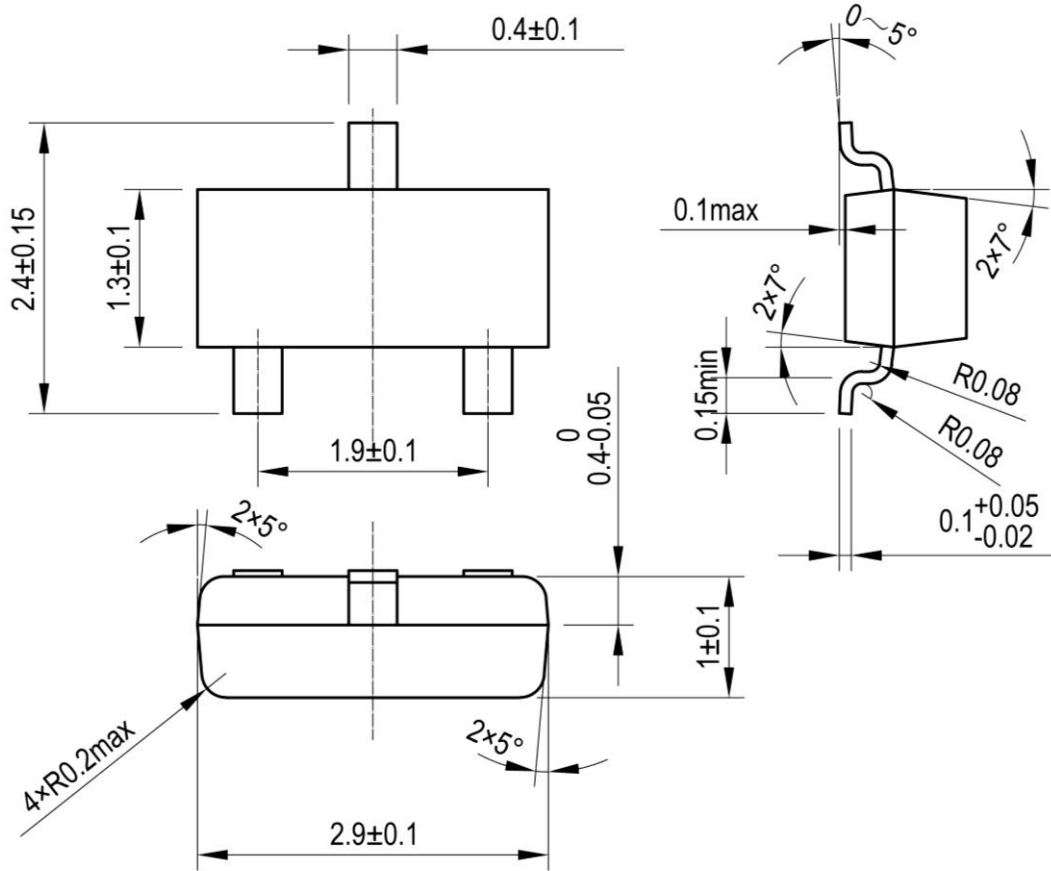
From the above function, we can see the depletion mode MOSFET operate in sub-threshold region, the  $V_{out}$  is always below or closed to the threshold voltage or Gate-to-Source Cut-off Voltage  $V_{GS(OFF)}$ , no matter how the input voltage  $V_{in}$  changes. Therefore, in addition to provide power for load like IC, the output voltage  $V_{out}$  can be clamped to the  $V_{GS(OFF)}$ , the IC is then protected from variable voltage or current. DMZ1315E/DMX1315E can support up to 130V input voltage.  $V_{out}$  and  $V_{in}$  have relations following the formulas:



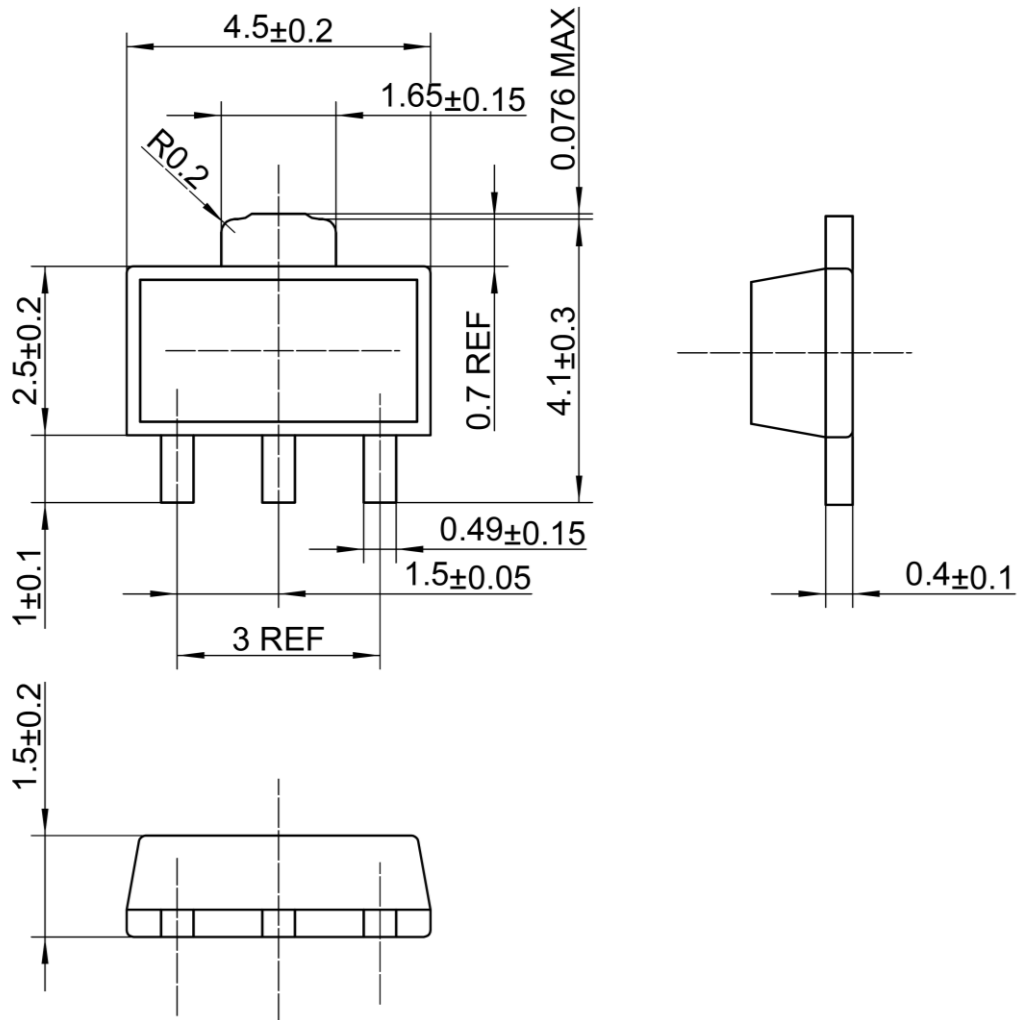
*If  $V_{in} < |V_{GS(OFF)}|$ , then  $V_{out} \approx V_{in}$*

*If  $V_{in} \geq |V_{GS(OFF)}|$ , then  $V_{out} \leq |V_{GS(OFF)}|$*

The Ultrahigh  $V_{th}$  Depletion Mode Power MOSFET--DMZ1315E/DMX1315E, was developed by ARK Microelectronics proprietary and patent technology. The threshold voltage  $V_{GS(OFF)}$  of DMZ1315E/ DMX1315E is between -17V and -27V, can provide sufficient voltage for load such like a PWM IC in the primary side of a Flyback converter.

**Package Dimensions**
**SOT-23**


SOT-89





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